L Number	Hits	Search Text	DB	Time stamp
1	50	((((heat near (sink or spreaderor pipe)) with ((chip or die) and adhesive)) and (@ad<19991230)) and (adhesive near epoxy)) and ((adhesive or epoxy) with cur$3)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 15:15
2	1	(((((heat near (sink or spreaderor pipe)) with ((chip or die) and adhesive)) and (@ad<19991230)) and (adhesive near epoxy)) and ((adhesive or epoxy) with cur$3)) and microwave	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 15:15
-	1	("6191360").PN.	USPAT	2004/02/12 13:09
-	1	("6306680").PN.	USPAT	2004/02/12 13:12
-	1158	(heat near (sink or spreaderor pipe)) with ((chip or die) and adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 13:16
-	701	((heat near (sink or spreaderor pipe)) with ((chip or die) and adhesive)) and (@ad<19991230)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 13:16
-	126	(((heat near (sink or spreaderor pipe)) with ((chip or die) and adhesive)) and (@ad<19991230)) and (adhesive near epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 13:24
-	122	(((heat near (sink or spreaderor pipe)) with ((chip or die) and adhesive)) and (@ad<19991230)) and (adhesive near epoxy)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 13:29
-	50	((((heat near (sink or spreaderor pipe)) with ((chip or die) and adhesive)) and (@ad<19991230)) and (adhesive near epoxy)) and ((adhesive or epoxy) with cur$3)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 15:14